

Atty. Docket No. **YOR920040553US1**

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<p>1. Name of conveying party(ies):</p> <p>Brian A. Floyd Ullrich R. Pfeiffer Scott K. Reynolds</p> <p>Additional name(s) of conveying party(ies) attached? <u> </u> Yes <u> X </u> No</p>	<p>2. Name and address of receiving party(ies):</p> <p>Name: International Business Machines Corporation Address: New Orchard Road Armonk, NY 10504</p> <p>Additional name(s) & addresses attached? <u> </u> Yes <u> X </u> No</p>
<p>3. Nature of conveyance:</p> <p><u> X </u> Assignment</p> <p>Execution Date(s): <u>Feb. 28, 2005; March 01, 2005</u></p>	<p>4. Patent Application number(s)</p> <p>11/029,518 Filed 01/05/05</p> <p>Execution Date(s): <u>Feb. 28, 2005; March 01, 2005</u></p>
<p>5. Name and address of party to whom correspondence concerning document should be mailed:</p> <p>Name: Thu Ann Dang Address: IBM Corporation Intellectual Property Law Dept. P.O. Box 218 Yorktown Heights, NY 10598</p>	<p>6. Total number of applications involved: <u> 1 </u></p> <p>7. Total fee (37 CFR 3.41): \$40.00</p> <p><u> X </u> Charge to Deposit Account No.: <u>09-0468</u></p>

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Stephen C. Kaufman (Reg. No. 29,551)

Name of Person Signing

Stephen C. Kaufman
Signature

MAR 4, 2005
Date

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PATENT

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(JOINT FORM)

(IBM Docket) YOR920040553US1

Assignment

Whereas, we

INVENTOR
AND CITY(1) Brian A. Floyd
County of Westchesterof Cortland Manor
and State of New YorkINVENTOR
AND CITY(2) Ullrich R. Pfeiffer
County of Putnamof Carmel
and State of New YorkINVENTOR
AND CITY(3) Scott K. Reynolds
County of Westchesterof Granite Springs
and State of New York

have invented certain improvements in

TITLE

ON-CHIP CIRCUIT PAD STRUCTURE

DATES THAT
INVENTORS
SIGNED THE
DECLARATIONand executed, respectively, a United States patent application therefor on
(1) *February 28*, 2005, and (2) *March 01* 2005,
(3) *February 28* 2005, and

Whereas, INTERNATIONAL BUSINESS MACHINES CORPORATION, a corporation of New York, having a place of business at Armonk, New York 10504, (hereinafter called IBM), desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, we, the above named, hereby sell, assign, and transfer to IBM, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the inventions set forth in said applications to IBM, its successors and assigns; and we hereby agree that IBM may apply for foreign Letters Patent on said invention and we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by IBM.

Signed and sealed

CITY AND
DATE(1) at *Yorktown Heights, NY*
on *Feb. 28*, 2005,

Brian A. Floyd SIGNATURE
(Brian A. Floyd) INVENTOR
FIRST NAME MIDDLE INITIAL LAST NAME

(JOINT FORM)

(IBM Docket) YOR920040553US1

CITY AND (2) at Yorktown Heights
DATE on 03/01/05 2005, Ulrich R. Pfeiffer SIGNATURE
(Ulrich R. Pfeiffer) INVENTOR
FIRST NAME MIDDLE INITIAL LAST NAME

CITY AND (3) at Yorktown Heights NY
DATE on 2/28 2005, Scott K. Reynolds SIGNATURE
(Scott K. Reynolds) INVENTOR
FIRST NAME MIDDLE INITIAL LAST NAME